

[ABSTRACT OF THE DISCLOSURE]

The present invention provides a film for a spacer applied to a multi-chip package and a method of forming a spacer using the same. The film for a spacer according to the present
5 invention includes a first film, and an adhesive layer disposed on a lower portion of the first film. The film for a spacer according to the present invention includes the first film instead of a dummy wafer, wherein the product of a storage modulus and an amount of curl is 10 GPa•mm to 200 GPa•mm.
10 Accordingly, it is possible to suppress die recognition failure occurring in the dicing process and improve pickup ability.

FIG. 5